ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

Generic Copy

27-APR-2004

SUBJECT: ON Semiconductor Final Product/Process Change Notification #13452

TITLE: Final PCN for Qualification of QFN 2X2.2MM at ON Seremban, Malaysia

EFFECTIVE DATE: 27-Jun-2004

AFFECTED CHANGE CATEGORY: ON Semiconductor Assembly Site

AFFECTED PRODUCT DIVISION: Analog Products

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Representative or Anju Parasher <R16742@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Representative
or Shannon Riggs <R13350@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact Sales Representative or Shannon Riggs <R13350@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:
ON Semiconductor is pleased to announce expanded assembly capacity for 2x2.2mm QFN Analog product utilizing the ON Seremban, Malaysia facility. Testing of this product will be performed by ON Semiconductor in the Seremban, Malaysia facility. The affected device is currently manufactured in ASAT, Hong Kong. After expiration of this PCN, the device listed below may be assembled at either manufacturing location.

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RELIABILITY DATA SUMMARY:

Reliability Test Results:
2x2.2mm QFN NCS2200SQLT1, 3 assembly lots:

TEST	Conditions	Results(#fail/totalSS)
HTOL	Ta=125deg C, 504hrs	0/231
HTB	Ta=150deg C, 504hrs	0/231
PreCond(PC)	MSL1, 260deg C	0/693
PC-TC	-65/+150C for 500cycles	0/231
PC-AC	121C/100%RH/15psig 96hrs	0/231
PC-HAST	130C/85%RH 96 hrs	0/231

ELECTRICAL CHARACTERISTIC SUMMARY:

All product performance meets current datasheet specifications.

CHANGED PART IDENTIFICATION:

Product manufactured after WW25, 2004 may be manufactured at either assembly location.
Site code traceability will be maintained.

AFFECTED DEVICE LIST :

PART
NCS2200SQLT1